

2304051441 Alternate PCB Supplier for xGM210P Modules

PCN Issue Date: Apr 05, 2023 Effective Date: Jul 11, 2023

PCN Type: Assembly

Description of Change

Silicon Labs is pleased to announce the successful qualification of a new Printed Circuit Board (PCB) supplier for xGM210P modules in Ryder. Upon PCN effective date, Silicon Labs will begin shipping the modules listed below with new PCB supplier.

Reason for Change

New PCB supplier qualification to mitigate supply constraint.

Impact on Form, Fit, Function, Quality, Reliability

There is no change in form, fit, function, quality & reliability performance.

Product Identification

This notification includes both standard and customer-specific part numbers. An asterisk * represents a number or letter (one or more) in a customer-specific part number.

Existing Part # BGM210PA22JIA2 BGM210PA22JIA2R BGM210PA32JIA2 BGM210PA32JIA2R BGM210PB22JIA2 BGM210PB22JIA2R BGM210PB32JIA2 BGM210PB32JIA2R MGM210PA22JIA2 MGM210PA22JIA2R MGM210PA32JIA2 MGM210PA32JIA2R MGM210PB22JIA2 MGM210PB22JIA2R MGM210PB32JIA2 MGM210PB32JIA2R MM21PA3IP*A2 MM21PA3IP*A2R BGM210PB*1A2

BGM210PB*1A2R

Last Date of Unchanged Product: Jul 11, 2023

Qualification Samples

Samples available upon request.

Customer Response

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change, Ref. JEDEC-J-STD-046.

To request further data or inquire about this notification, please contact your Silicon Labs sales representative. A list of Silicon Labs sales representatives is available at http://www.silabs.com.

Customers may approve early PCN acceptance by emailing approval, along with PCN # to PCNEarlyAcceptance@silabs.com

User Registration

Register today to create your account on Silabs.com. Your personalized profile allows you to receive technical document updates, new product announcements, "how-to" and design documents, product change notices (PCN) and other valuable content available only to registered users. http://www.silabs.com/profile

Qualification Data

Qualification report is attached.

BGM210P, MGM210P Qualification Report



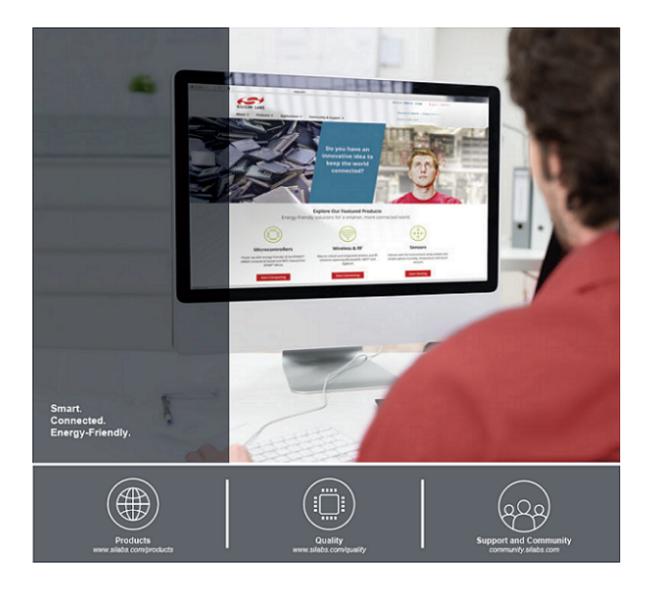
BGM210P, N	BGM210P, MGM210P, Ryder China, USI Taiwan								
Test Name	Test Condition	Qualification	Start	Fall/Pass or End	Notes	Summary	Status		
	Accelerated Environment S	Stress Tests							
Preconditioning	JESD22-A113 MSL3: 260°C 30°C / 60%RH / 192 Hr	1 lot, N=>10	Q046125 Q044122 Q046242 Q050079	0/12 0/24 0/30 0/12	4 3 3 5	4 lots 0/78	Pass		
Temp Cycle	JESD22-A104 Cond G: -40°C to 125°C 850 cycles	1 lot, N=>10	Q046207 Q044119 Q050132	0/10 0/12 0/12	1,4 1,3 1.5	3 lots 0/34	Pass		
Temp Cycle	JESD22-A104 Cond N: -40°C to 85°C 1500 cycles	1 lot, N=>10	Q044120	0/12	1,3	1 lot 0/12	Pass		
Temp Humidity Bias	JESD22-A101 85°C, 85% RH 500 hours	1 lot, N=>25	Q046243	0/30	1, 2, 3	1 lot 0/30	Pass		
Test Group C -	Package Assembly Integri	ty Tests							
Mechanical Shock	JESD22-B110, Cond. B (1500g)	1 lot, N=>10	Q046221 Q044125 Q050123	0/10 0/10 0/10	4 3 5	3 lots 0/30	Pass		
Mechanical Vibration	JESD22-B103, Cond. 1 (20-2000Hz)	1 lot, N=>10	Q046222 Q044126 Q050124	0/10 0/10 0/10	4 3 5	3 lots 0/30	Pass		
Cleanliness Assessment	IPC-TM-650 2.3.28B	1 lot, N=>10	Q046223 Q044127 Q050131	0/10 0/10 0/10	4 3 5	3 lots 0/30	Pass		

Notes:

- 1. Parts are Pre-conditioned at MSL3/260°C
- 2. Additional stress test for BSH (Abbrev H3TRB)
- 3. Assembly in Ryder China
- 4. Assembly in USI Taiwan
- 5. Assembly in Ryder, China (KinWong PCB)

This report applies to the following part numbers:						
BGM210P						
MGM210P						

Approved by: Wilson Choy 1 of 1 Prepared on: 16-Mar-23



Disclaimer

Silicon Labs intends to provide customers with the latest, accurate, and in-depth documentation of all peripherals and modules available for system and software implementers using or intending to use the Silicon Labs products. Characterization data, available modules and peripherals, memory sizes and memory addresses refer to each specific device, and "Typical" parameters provided can and do vary in different applications. Application examples described herein are for illustrative purposes only. Silicon Labs reserves the right to make changes without further notice and limitation to product information, specifications, and descriptions herein, and does not give warranties as to the accuracy or completeness of the included information. Silicon Labs shall have no liability for the consequences of use of the information supplied herein. This document does not imply or express copyright licenses granted hereunder to design or fabricate any integrated circuits. The products are not designed or authorized to be used within any Life Support System without the specific written consent of Silicon Labs. A "Life Support System" is any product or system intended to support or sustain life and/or health, which, if it fails, can be reasonably expected to result in significant personal injury or death. Silicon Labs products are not designed or authorized for military applications. Silicon Labs products shall under no circumstances be used in weapons of mass destruction including (but not limited to) nuclear, biological or chemical weapons, or missiles capable of delivering such weapons.

Trademark Information

Silicon Laboratories Inc.®, Silicon Laboratories®, Silicon Labs®, SiLabs® and the Silicon Labs logo®, Bluegiga®, Bluegiga Logo®, Clockbuilder®, CMEMS®, DSPLL®, EFM®, EFM32®, EFR, Ember®, Energy Micro, Energy Micro logo and combinations thereof, "the world's most energy friendly microcontrollers", Ember®, EZLink®, EZRadio®, EZRadioPRO®, Gecko®, ISOmodem®, Micrium, Precision32®, ProSLIC®, Simplicity Studio®, SiPHY®, Telegesis, the Telegesis Logo®, USBXpress®, Zentri and others are trademarks or registered trademarks of Silicon Labs. ARM, CORTEX, Cortex-M3 and THUMB are trademarks or registered trademarks of ARM Holdings. Keil is a registered trademark of ARM Limited. All other products or brand names mentioned herein are trademarks of their respective holders.



Silicon Laboratories Inc. 400 West Cesar Chavez Austin, TX 78701